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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/814,570	03/31/2004	Teng-Wang Huang	MAIKP131US	6882
	7590 04/16/2007 & ASSOCIATES, LLC	,	EXAMINER	
NATIONAL CI	ITY BANK BUILDING		DEO, DUY VU NGUYEN	
629 EUCLID A CLEVELAND,	VE., SUITE 1000 OH 44114		ART UNIT	PAPER NUMBER
,			1765	
SHORTENED STATUTOR	Y PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE	
3 MOI	NTUS	04/16/2007	DAT	DED

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

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	Application No.	Applicant(s)	
	10/814,570	HUANG ET AL.	
Office Action Summary	Examiner	Art Unit	
·	Duy-Vu N. Deo	1765	
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the	correspondence address -	-
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be will apply and will expire SIX (6) MONTHS from the cause the application to become ABANDON	ON. imely filed m the mailing date of this communica IED (35 U.S.C. § 133).	
Status			
'=	action is non-final.		· i-
3) Since this application is in condition for allower			; IS
closed in accordance with the practice under E	ex parte Quayle, 1955 C.D. 11,	155 U.G. 215.	
Disposition of Claims			
 4) ☐ Claim(s) 1-20 is/are pending in the application. 4a) Of the above claim(s) is/are withdraw 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-20 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or 	wn from consideration.		
Application Papers			
9)☐ The specification is objected to by the Examine			
10) The drawing(s) filed on is/are: a) acce	•	Examiner	
Applicant may not request that any objection to the			
Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Ex	ion is required if the drawing(s) is o	bjected to. See 37 CFR 1.12	• •
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the prior application from the International Bureau * See the attached detailed Office action for a list of	s have been received. s have been received in Applica rity documents have been recei u (PCT Rule 17.2(a)).	tion No ved in this National Stage	
Attachment(s)			
Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summan Paper No(s)/Mail S) Notice of Informal S) Other:	Date	
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DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-20 are rejected under 35 U.S.C. 103(a) as being unpatentable over admitted prior art and in view of Chen et al. (US 6,468,362).

Admitted prior art teaches a wet etching method of a substrate to form deep trench for a DRAM cell comprising: etching the substrate in a first HF tank (claimed vessel); rinsing substrate in second tank; etching the substrate in a third NH4OH tank; rinsing the substrate in a fourth tank; and drying the substrate (pages 1-2 of the specification). Unlike claimed invention, admitted prior art doesn't describe the first rinsing agent comprising at least one wetting agent. Chen describes a method for cleaning the substrate wherein the cleaning solution comprises of a surfactant (claimed rinsing comprising wetting agent) (col. 2, line 65-67; col. 7, line 7-20). It would have been obvious for one skilled in the art to modify admitted prior art in light of Chen by using a cleaning solution with a surfactant because Chen teaches that it would clean the substrate with minimal water marks and residues (col. 1, line 47-57; col. 10, line 31-36). Admitted prior art teaches of successively performing these etching and rinsing steps

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before the drying step (page 1, line 35-39). The wetting agent or surfactant would also provide the benefit of reduces a surface tension associated with the second etchant.

Referring to claims 6, 17, Chen describes the wetting agent concentration is 0.01-0.1% by V (claimed 0.01-0.1% by wt).

Referring to claims 7, 9, 18, 19, 20, admitted prior art describes the deep trench has aspect ratio of 50 or more are possible (page 1, line 30-35).

Response to Arguments

- 3. Applicant's argument that Chen teaches of rinsing the wafer with water and then drying the wafer is acknowledged. However, in another embodiment he teaches of rinsing with the solution that having surfactant and stopping before the surfactant is completely removed (fig. 1). Therefore, he does suggest keeping the surfactant on the wafer.
- 4. Applicant's arguments that Chen teaches of drying the wafer <u>prior to performing</u> <u>any other process steps</u> and that a combination would require two drying steps to be performed are found unpersuasive because he doesn't explicitly describe drying the wafer <u>prior to performing any other process steps</u> in the description. Even though he describes the cleaning process includes starting step of applying the cleaning solution and then the last step of drying; however, he doesn't teach that the drying step has to be done prior to performing any other steps. Furthermore, Chen is a secondary reference and the main reference or the main process described above concerns about a wet etching method to form deep trench, wherein the process includes rinsing steps. The drying step is done at the end of the whole process as described by the admitted

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prior art above. Therefore, one skilled in the art who forms a deep trenches would perform the drying step at the end of the whole process but not perform during the process since admitted prior art doesn't teach so.

- 5. Also, Chen describes with the surfactant containing solutions, the substrate can be effectively cleaned, rinsed, and dried with minimal water marks, not just during the drying of the wafer (col. 10, line 31-36).
- 6. In response to applicant's argument that the at least one wetting agent reduces a surface tension associated with the second etchant, the fact that applicant has recognized another advantage which would flow naturally from following the suggestion of the prior art cannot be the basis for patentability when the differences would otherwise be obvious. See *Ex parte Obiaya*, 227 USPQ 58, 60 (Bd. Pat. App. & Inter. 1985).

Conclusion

7. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any

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extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Duy-Vu N. Deo whose telephone number is 571-272-1462. The examiner can normally be reached on Mon-Fri.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on 571-272-1465. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

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